



NOTES:

1. ALL EXPOSED METALIZED AREA ON CERAMIC SHALL BE GOLD PLATED, .005 MICRO NICHES MIN. OVER 100 MICRO INCHES NICKEL MIN.
2. SEAL RING AND DIE ATTACH PAD ARE NOT GROUNDED TO A LEAD.
3. MATERIAL:
 - A. CERAMIC: 90-92% AL₂O₃ BLACK.
 - B. METALLIZATION: REFACTORY METAL.
 - C. LEADFRAME: ALDLY-42 OR EQUIVALENT; PLATING SHALL BE 50 MICRO NICHES GOLD MIN. OVER 100 MICRO INCHES MICKEL MIN.
4. CENTER LINES OF LEADS 5 & 23 SHALL NOT BE MORE THAN ±.004 OFFSET FROM THE CENTER LINES OF THE RESPECTIVE LEAD CONTACT PADS.
5. PACKAGE SHALL CONFORM TO MIL SPEC MIL-M-38510, SECTION 3 AS APPLICABLE CURRENT REV. AS P.O. IS PLACED.
6. ACCEPTANCE CRITERIA FOR THIS PACKAGE IS SPEC # 7500020 (AS APPLICABLE)
7. TOLERANCES ARE ±1% UNLT .005"
8. EQUIVALENT TO KYOCERA PG-F91 D98
9. THE ESD TRIANGLE AND THE "DOT" ON THE BACK OF THE PACKAGE ARE REQUIRED AT THE LOCATION SHOWN. EXACT SIZE OF THE TRIANGLE AND DOT ARE AT THE BOTTOM OF THE DRAWING. EACH MUST BE LARGE ENOUGH TO BE VISIBLE TO THE USER. THE USER SHALL BE RESPONSIBLE TO VERIFY THE SIZE OF THIS PACKAGE THAT DO NOT HAVE THESE FEATURES, CAN AND MUST BE USED UNTIL EXHAUSTED.)
10. PIN ONE IDENTIFIER CONFIGURATION MAY VARY (VENDOR'S OPTION).

REV	Part or Identifying No.	Case	Description	Material or Note	Quantity or Remarks
001	5-7-50	5-7-50	40 LEAD CORP		
002	5-7-50	5-7-50	2507 x 2507 D/A PAD		
003	5-7-50	5-7-50	3300194		
004	5-7-50	5-7-50	3300194		
005	5-7-50	5-7-50	3300194		
006	5-7-50	5-7-50	3300194		
007	5-7-50	5-7-50	3300194		
008	5-7-50	5-7-50	3300194		
009	5-7-50	5-7-50	3300194		
010	5-7-50	5-7-50	3300194		
011	5-7-50	5-7-50	3300194		

REV	DESCRIPTION	DATE	APPROVAL